

**In the Claims:**

1-10. (Canceled).

11. (Currently Amended) An integrated circuit package comprising:  
a first leadframe, having a first side and a second side, opposite the first side;  
a second leadframe laminated to a portion of a surface the first side of said first leadframe  
thereby providing a multi-layer laminated leadframe;  
a semiconductor die mounted to another portion of said first side surface of said first  
leadframe; and  
a plurality of contact balls mounted on said semiconductor die.

12. (Previously Presented) An integrated circuit package comprising:  
a first leadframe;  
a second leadframe laminated to a portion of said first leadframe thereby providing a multi-  
layer laminated leadframe;  
a semiconductor die having opposing first and second surfaces, the first surface of said  
semiconductor die being mounted to another portion of said first leadframe; and  
a third lead frame laminated to at least a portion of said second surface of said  
semiconductor die.

13. (Currently Amended) The integrated circuit package according to claim 11, wherein  
said first leadframe comprises a copper strip having silver plating on one surface the second side  
and said second leadframe is soldered to the first side of the first leadframe an opposing second  
surface thereof.

14. (Previously Presented) The integrated circuit package according to claim 11, wherein said second leadframe comprises a copper strip having solder plating on one surface and being soldered to said first leadframe on an opposing second surface thereof.

15. (Original) The integrated circuit package according to claim 12, wherein said third leadframe comprises a copper strip having a solder plating on one surface and being soldered to said first leadframe on an opposing second surface thereof.

16. (Previously Presented) The integrated circuit package according to claim 11 wherein said semiconductor die is coated with at least one of titanium, tungsten, gold, or a combination thereof for soldering.